

CH03-CD : SIM CARD CONNECTOR SMT TYPE 6 CONTACTS OPTIONAL HEIGHT

Specification

1.General Information

- Contact principle: Friction technology
- Mounting Type: SMT
- Durability: 10,000 cycles min. Δ
- Voltage Rating: 30V AC
- Current Rating: 1A Max, 10uA Min

2.Electrical Specification

- Contact Resistance: 50m ohms Max
- Insulation Resistance: 1000MOhm Min
- Dielectrical Withstanding Voltage: 500V AC R.M.S. 1 Min(Sea Level)

3.Mechanical Specification

- Contact Force: 0.2N~0.6N
- Data Contact Material: Copper Alloy
- Insulation Material: Thermoplastic, UL 94V-0
- Data Contacts Plating: Gold Plated Over Nickel

4.SOLDERABILITY

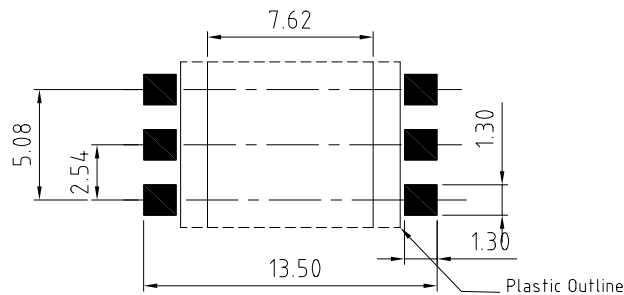
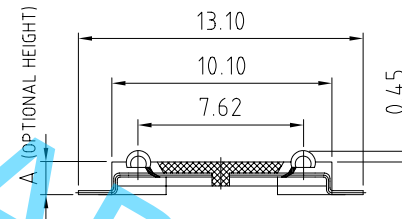
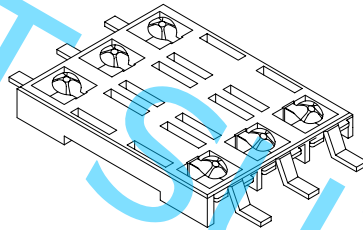
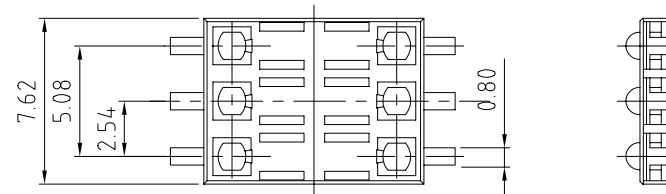
- WAVE: NOT APPLICABLE
- IR REFLOW: 260°C, 5 SEC. MAX. Δ Δ
- MANUAL SOLDERING: 360°C, 3 SEC. MAX.

5.Environmental Specification

- Operating Temperature: -20°C~+70°C
- Operating Humidity: 20%~95% RH

NOTES:

- 1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT. Δ



RECOMMENDED PCB LAYOUT

HOW TO ORDER



- A HEIGHT
- 08 = 0.85
- 10 = 1.00
- 12 = 1.20
- 15 = 1.50

- PACKAGING OPTIONS
- Δ T = TUBE
- R = REEL

REV.	DATE & DRN
1.0	13/12/04 - CHC RELEASE
1.1	21/03/06 - NYW
1.2	ADD ROHS OPTION
1.3	27/04/06 - NYW
1.4	14/07/06 - NYW
1.5	29/05/07 - CHC
1.6	06/12/07 - NYW
1.7	18/06/09 - NYW

Scale: 4:1	THIRD ANGLE	Unstated Tolerances: .X ±0.38 .XX ±0.25	Material SEE NOTE
Drawn: CHC			
App'd: NYW	Title SIM Card Acceptor		NOT TO SCALE
Date: 18 JUN '09	Revision : 1.7		Unit : mm

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Type: CH03-CD
CH03-CD
Drawing Number:
Sheet 1 of 1
Drawing C E and O E